

# SOT100A

hermetic ceramic surface mounted package; 4 leads

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	R (radial)
<b>Package type descriptive code</b>	CRDB4
<b>Package type industry code</b>	CRDB4
<b>Package style descriptive code</b>	CRDB (ceramic radial disk-button)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	C (ceramic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	16-3-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.4	-	2.5	2.6	mm
E	package width	2.34	-	2.49	2.64	mm
A	seated height	0.81	-	1.06	1.31	mm
n <sub>2</sub>	actual quantity of termination	-	-	4	-	



2. Package outline

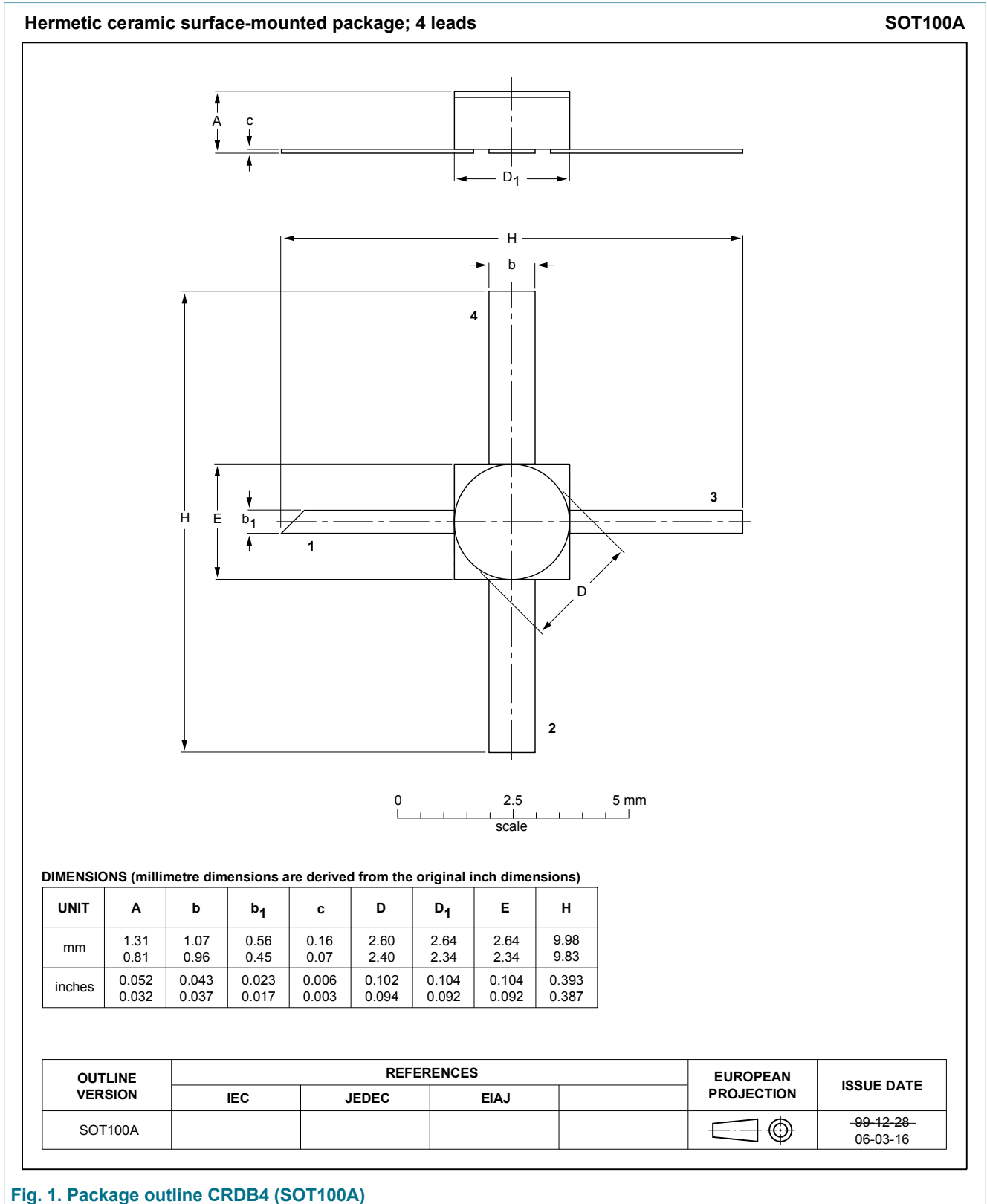


Fig. 1. Package outline CRDB4 (SOT100A)

### 3. Legal information

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